1. Package summary

Terminal position codeQ (quad)Package type descriptive codeLQFP64

Package type industry code LQFP64

Package style descriptive code

Package style suffix code NA (not applicable)

LQFP (low profile quad flat package)

Package body material typeP (plastic)IEC package outline code136E06JEDEC package outline codeMS-026

Mounting method type S (surface mount)

Issue date 20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
Α	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination	-	-	64	-	



plastic low profile quad flat package; 64 leads; body 7 x 7 x 1.4 mm

2. Package outline

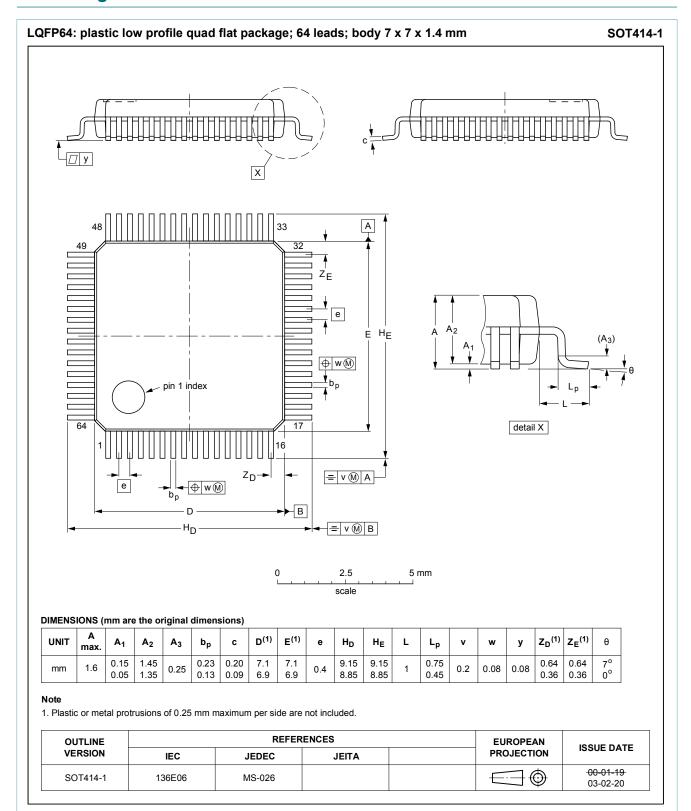
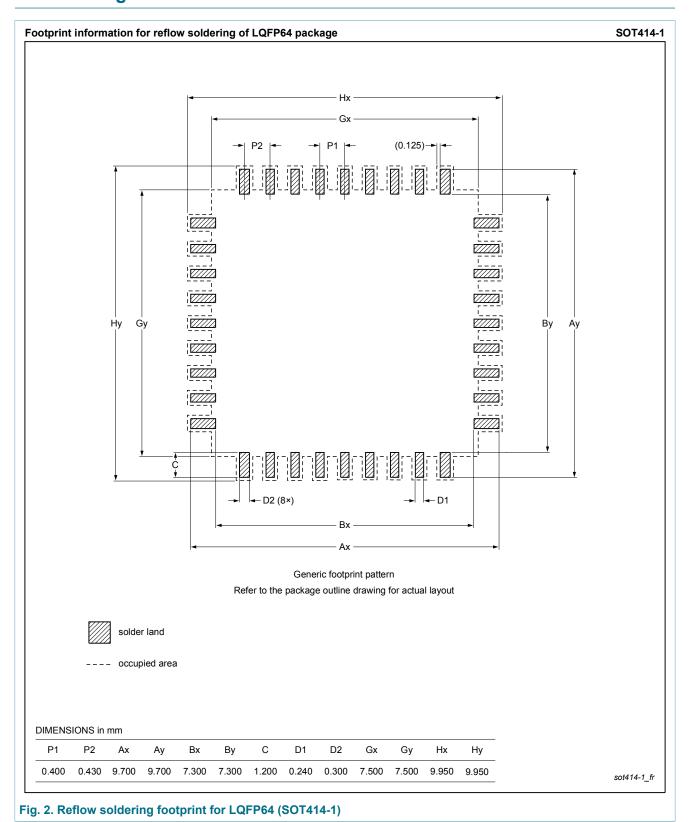


Fig. 1. Package outline LQFP64 (SOT414-1)

plastic low profile quad flat package; 64 leads; body 7 x 7 x 1.4 mm

3. Soldering



plastic low profile quad flat package; 64 leads; body 7 x 7 x 1.4 mm

4. Legal information

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plastic low profile quad flat package; 64 leads; body 7 x 7 x 1.4 mm

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